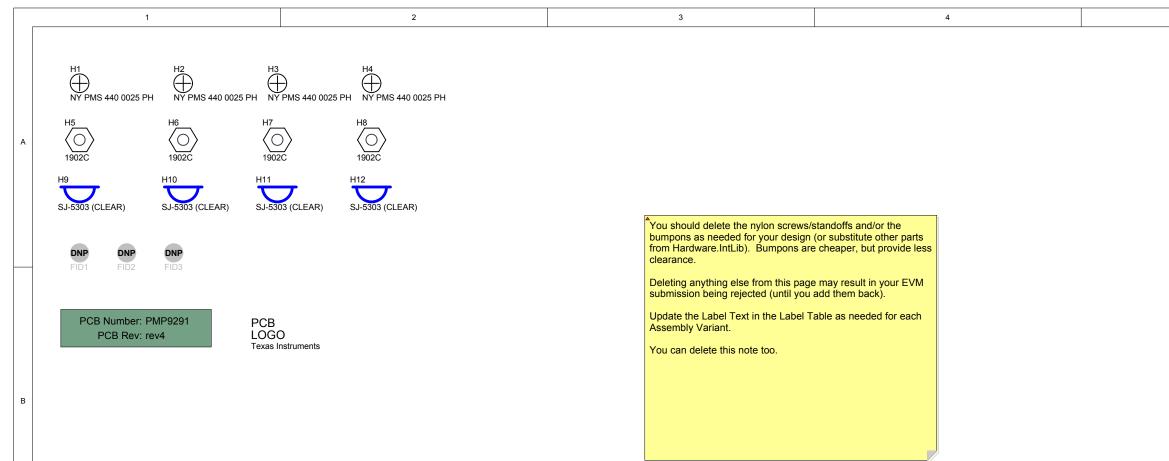


	Designed for: Public Release		ate: 9/18/2015	
	Project Title: LM5017 Sync Flybuck			TEXAS
Rev: rev4	Sheet Title: *			INSTRUMENTS
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	File: PMP9291 Rev4 Schema	atic.SchDoc	Size: B	http://www.ti.com
rian	Contact: http://www.ti.com/support		© Texas Instruments 2013	
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LBL1	
PCB Label	
Size: 0.65" x 0.20 "	

ZZ1 Label Assembly Note This Assembly Note is for PCB labels only

ChangeMe! 001 002 ChangeMe!

Variant

Label Table Label Text

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ZZ2 Assembly Note These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

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ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

				Designed for: Public Relea	se Mod. Date: 9/18/2015	
				Project Title: LM5017 Sync	c Flybuck	TEXAS
			Number: PMP9291 Rev: rev4	Sheet Title:		
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warrant that this design will meet the s	pecifications, will be suitable for your application or fit for any particular	purpose, or will operate in an implementation. Texas Instruments and/or i	s Drawn By:	File: PMP9291 rev4 Hardw	/are_ANSI-B.SchDoc Size: B	http://www.ti.com
licensors do not warrant that the design	n is production worthy. You should completely validate and test your des	sign implementation to confirm the system functionality for your applicatio	n. Engineer: Hrag Kasparian	Contact: http://www.ti.com	/support	© Texas Instruments 2013
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